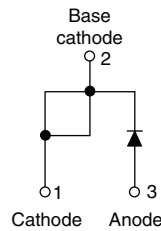


# **HEXFRED®** **Ultrafast Soft Recovery Diode, 8 A**


**TO-220AC**

## **FEATURES**

- Ultrafast and ultrasoft recovery
- Very low  $I_{RRM}$  and  $Q_{rr}$
- Designed and qualified according to JEDEC®-JESD47
- Material categorization:  
for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
Available

## **BENEFITS**

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

## **DESCRIPTION**

VS-HFA08TB120... is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 1200 V and 8 A continuous current, the VS-HFA08TB120... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current ( $I_{RRM}$ ) and does not exhibit any tendency to “snap-off” during the  $t_b$  portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA08TB120... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

## **PRODUCT SUMMARY**

Package	TO-220AC
$I_{F(AV)}$	8 A
$V_R$	1200 V
$V_F$ at $I_F$	2.4 V
$t_{rr}$ typ.	28 ns
$T_J$ max.	150 °C
Diode variation	Single die

## **ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	$V_R$		1200	V
Maximum continuous forward current	$I_F$	$T_C = 100\text{ °C}$	8	A
Single pulse forward current	$I_{FSM}$		130	
Maximum repetitive forward current	$I_{FRM}$		32	
Maximum power dissipation	$P_D$	$T_C = 25\text{ °C}$	73.5	W
		$T_C = 100\text{ °C}$	29	
Operating junction and storage temperature range	$T_J, T_{Stg}$		-55 to +150	°C



ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	$V_{BR}$	$I_R = 100\text{ }\mu\text{A}$	1200	-	-	V
Maximum forward voltage	$V_{FM}$	$I_F = 8.0\text{ A}$	-	2.6	3.3	
		$I_F = 16\text{ A}$	-	3.4	4.3	
		$I_F = 8.0\text{ A}$ , $T_J = 125\text{ }^{\circ}\text{C}$	-	2.4	3.1	
Maximum reverse leakage current	$I_{RM}$	$V_R = V_R\text{ rated}$	-	0.31	10	$\mu\text{A}$
		$T_J = 125\text{ }^{\circ}\text{C}$ , $V_R = 0.8 \times V_R\text{ rated}$	-	135	1000	
Junction capacitance	$C_T$	$V_R = 200\text{ V}$	-	11	20	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS ( $T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1.0\text{ A}$ , $dI_F/dt = 200\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	28	-	ns
	$t_{rr1}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	63	95	
	$t_{rr2}$	$T_J = 125\text{ }^{\circ}\text{C}$	-	106	160	
Peak recovery current	$I_{RRM1}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	4.5	8.0	A
	$I_{RRM2}$	$T_J = 125\text{ }^{\circ}\text{C}$	-	6.2	11	
Reverse recovery charge	$Q_{rr1}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	140	380	nC
	$Q_{rr2}$	$T_J = 125\text{ }^{\circ}\text{C}$	-	335	880	
Peak rate of recovery current during $t_b$	$dI_{(rec)M}/dt1$	$T_J = 25\text{ }^{\circ}\text{C}$	-	133	-	$\text{A}/\mu\text{s}$
	$dI_{(rec)M}/dt2$	$T_J = 125\text{ }^{\circ}\text{C}$	-	85	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	$T_{lead}$	0.063" from case (1.6 mm) for 10 s	-	-	300	$^{\circ}\text{C}$
Thermal resistance, junction to case	$R_{thJC}$		-	-	1.7	K/W
Thermal resistance, junction to ambient	$R_{thJA}$	Typical socket mount	-	-	40	
Thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, flat, smooth and greased	-	0.25	-	
Weight			-	6.0	-	g
			-	0.21	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-220AC	HFA08TB120			

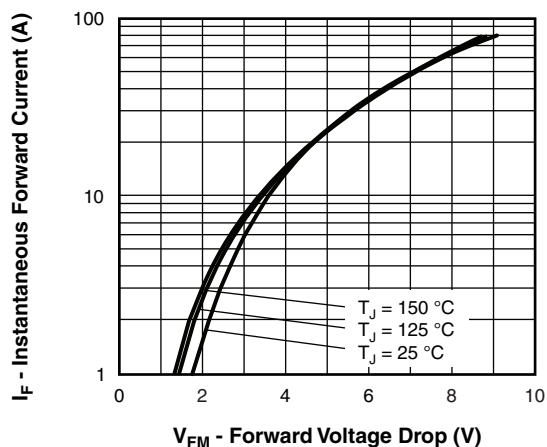


Fig. 1 - Maximum Forward Voltage Drop Characteristics

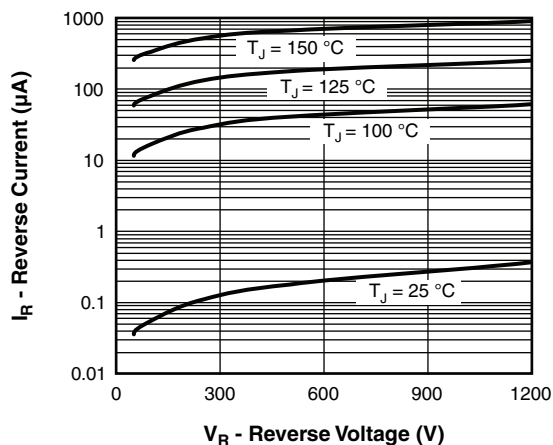


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

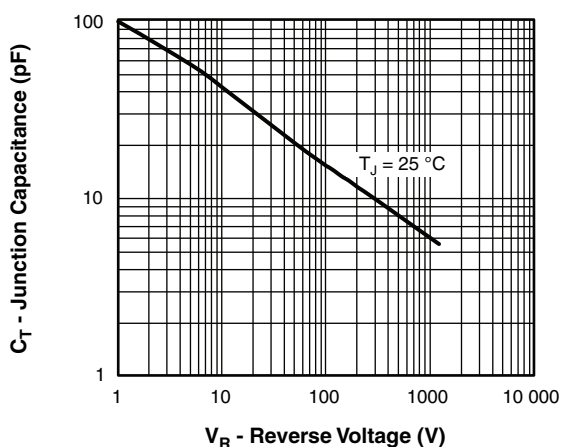
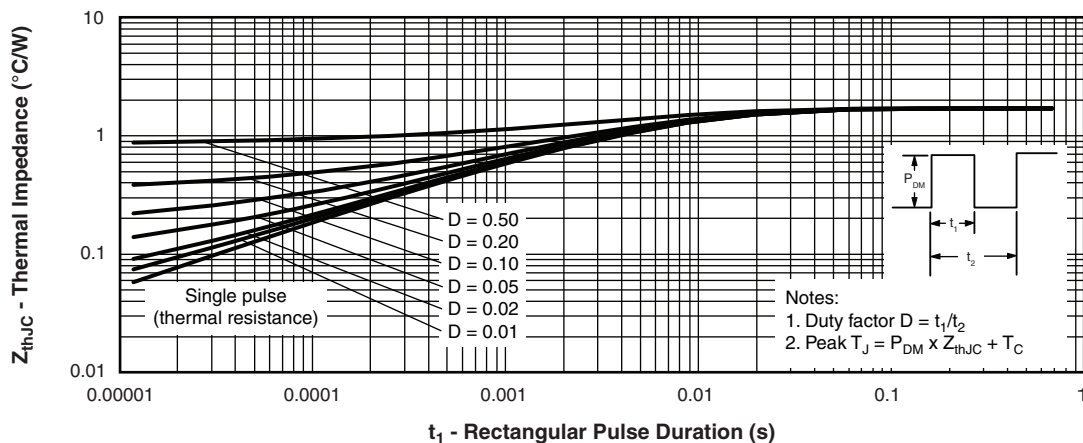


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

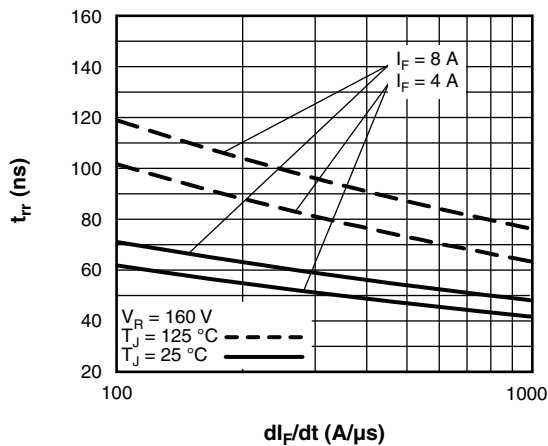


Fig. 5 - Typical Reverse Recovery Time vs.  $dI_F/dt$

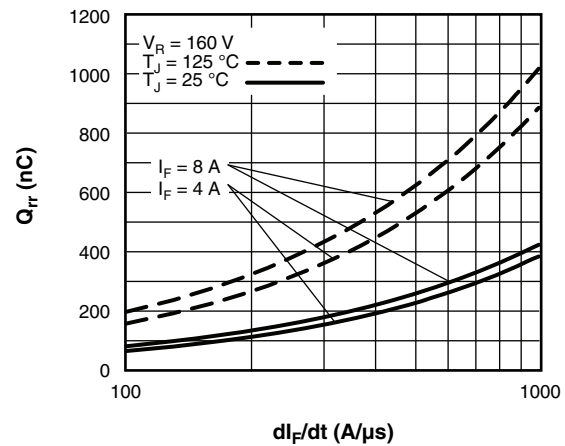


Fig. 7 - Typical Stored Charge vs.  $dI_F/dt$

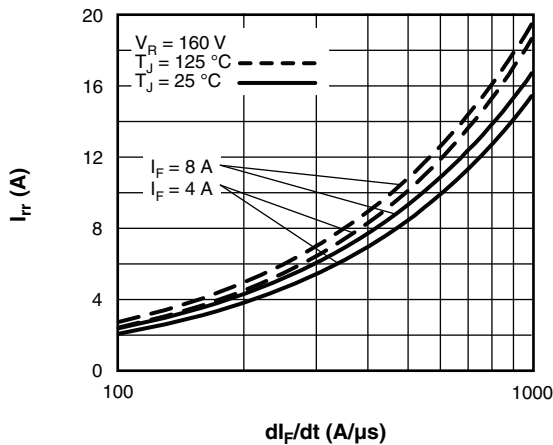


Fig. 6 - Typical Recovery Current vs.  $dI_F/dt$

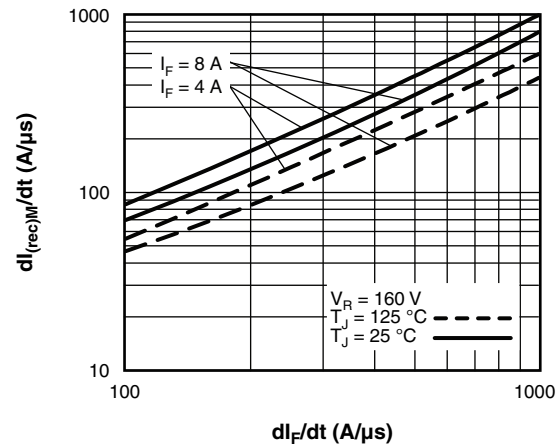


Fig. 8 - Typical  $dI_{(rec)M}/dt$  vs.  $dI_F/dt$

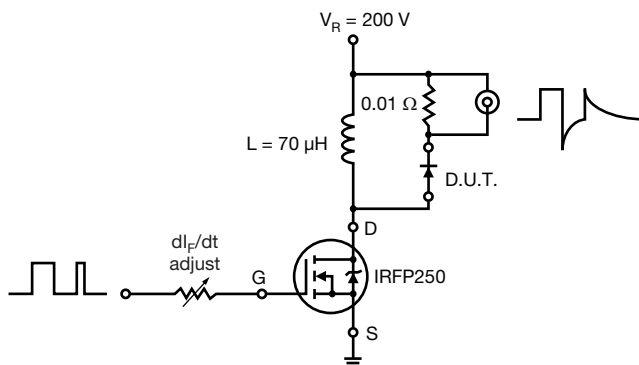


Fig. 9 - Reverse Recovery Parameter Test Circuit

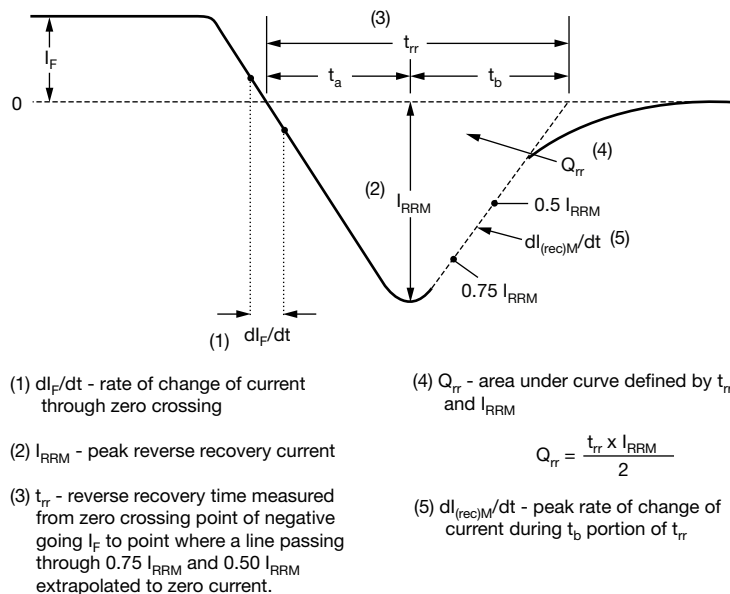


Fig. 10 - Reverse Recovery Waveform and Definitions



## ORDERING INFORMATION TABLE

Device code	VS-	HF	A	08	TB	120	PbF
	1	2	3	4	5	6	7

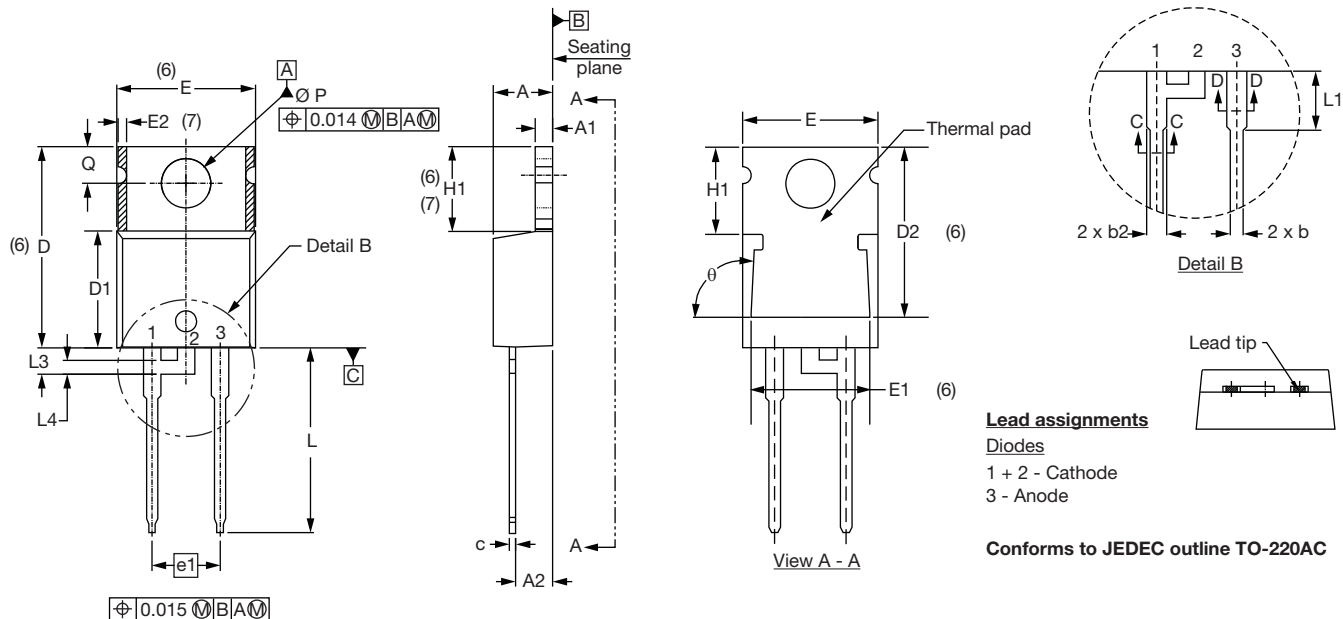
- 1** - Vishay Semiconductors product
- 2** - HEXFRED® family
- 3** - Electron irradiated
- 4** - Current rating (08 = 8 A)
- 5** - Package:  
TB = TO-220AC
- 6** - Voltage rating (120 = 1200 V)
- 7** - Environmental digit:  
PbF = lead (Pb)-free and RoHS-compliant  
-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-HFA08TB120PbF	50	1000	Antistatic plastic tube
VS-HFA08TB120-N3	50	1000	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95221">www.vishay.com/doc?95221</a>
Part marking information	TO-220ACPbF <a href="http://www.vishay.com/doc?95224">www.vishay.com/doc?95224</a>
	TO-220AC-N3 <a href="http://www.vishay.com/doc?95068">www.vishay.com/doc?95068</a>

### TO-220AC

**DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.56	2.92	0.101	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
c	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.25	0.585	0.600	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	12.88	0.460	0.507	6
E	10.11	10.51	0.398	0.414	3, 6

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
E1	6.86	8.89	0.270	0.350	6
E2	-	0.76	-	0.030	7
e	2.41	2.67	0.095	0.105	
e1	4.88	5.28	0.192	0.208	
H1	6.09	6.48	0.240	0.255	6, 7
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
L3	1.78	2.13	0.070	0.084	
L4	0.76	1.27	0.030	0.050	2
Ø P	3.54	3.73	0.139	0.147	
Q	2.60	3.00	0.102	0.118	
θ	90° to 93°		90° to 93°		

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC TO-220, D2 (minimum) where dimensions are derived from the actual package outline



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